



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUA250N08S5N020	Issued	17. May 2021
MA#	MA005413535		
Package	PG-HSOF-5-4	Weight*	370.68 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.336	1.17	1.17	11697	11697
leadframe	inorganic material	phosphorus	7723-14-0	0.015			39	
	non noble metal	iron	7439-89-6	0.048	0.01		131	
	non noble metal	copper	7440-50-8	48.418	13.06	13.07	130618	130788
wire	noble metal	gold	7440-57-5	0.051	0.01	0.01	138	138
encapsulation	inorganic material	zinc oxide	1314-13-2	1.393	0.38		3757	
	miscellaneous	miscellaneous	-	5.571	1.50		15029	
	plastics	epoxy resin	-	20.891	5.64		56360	
	inorganic material	silicon dioxide	60676-86-0	111.421	30.06	37.58	300584	375730
lead finish	non noble metal	tin	7440-31-5	3.673	0.99	0.99	9908	9908
plating	noble metal	silver	7440-22-4	0.015			41	41
solder	non noble metal	tin	7440-31-5	0.075	0.02		203	
	noble metal	silver	7440-22-4	0.094	0.03		254	
	non noble metal	lead	7439-92-1	3.596	0.97	1.02	9702	10159
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008			23	
	non noble metal	iron	7439-89-6	0.028	0.01		76	
	non noble metal	copper	7440-50-8	28.224	7.61	7.62	76140	76239
heatspreader	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
	non noble metal	iron	7439-89-6	0.143	0.04		385	
	non noble metal	copper	7440-50-8	142.638	38.49	38.54	384799	385300
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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